MC10E154, MC100E154

5V ECL 5-Bit 2:1 Mux-Latch

The MC10E/100E154 contains five 2:1 multiplexers followed by transparent latches with differential outputs. When both Latch Enables (LEN1, LEN2) are LOW, the latch is transparent, and output data is controlled by the multiplexer select control, SEL. A logic HIGH on either LEN1 or LEN2 (or both) latches the outputs. The Master Reset (MR) overrides all other controls to set the Q outputs LOW.

The 100 series contains temperature compensation.

- 850 ps Maximum LEN to Output
- 825 ps Maximum D to Output
- Differential Outputs
- Asynchronous Master Reset
- Dual Latch-Enables
- PECL Mode Operating Range: V_{CC} = 4.2 V to 5.7 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = −4.2 V to −5.7 V
- Internal Input 50 KΩ Pulldown Resistors
- ESD Protection: Human Body Model; > 2 KV, Machine Model; > 200 V
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity Level 1
  For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL 94 V−0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 237 Devices

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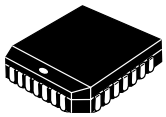
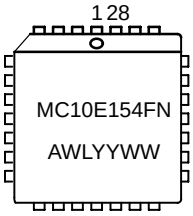
MARKING DIAGRAMS



PLCC−28
FN SUFFIX
CASE 776

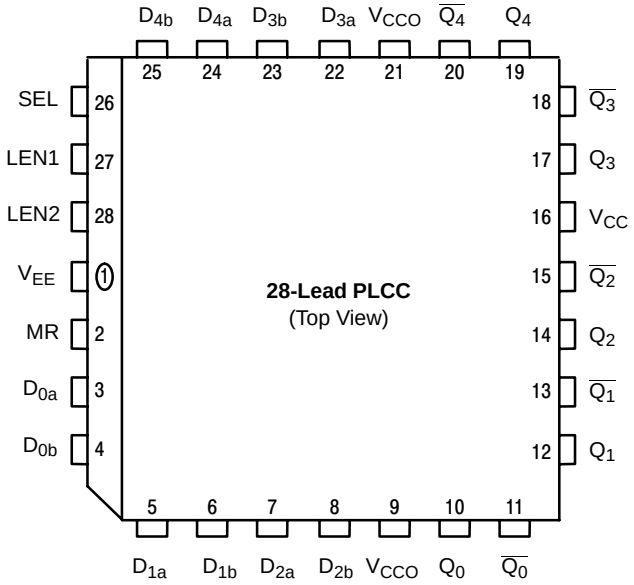


A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping†
MC10E154FN	PLCC−28	37 Units/Rail
MC10E154FNR2	PLCC−28	500 Units/Reel
MC100E154FN	PLCC−28	37 Units/Rail
MC100E154FNR2	PLCC−28	500 Units/Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



* All V_{CC} and V_{CCO} pins are tied together on the die.

Warning: All V_{CC}, V_{CCO}, and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. LOGIC DIAGRAM AND PINOUT ASSIGNMENT

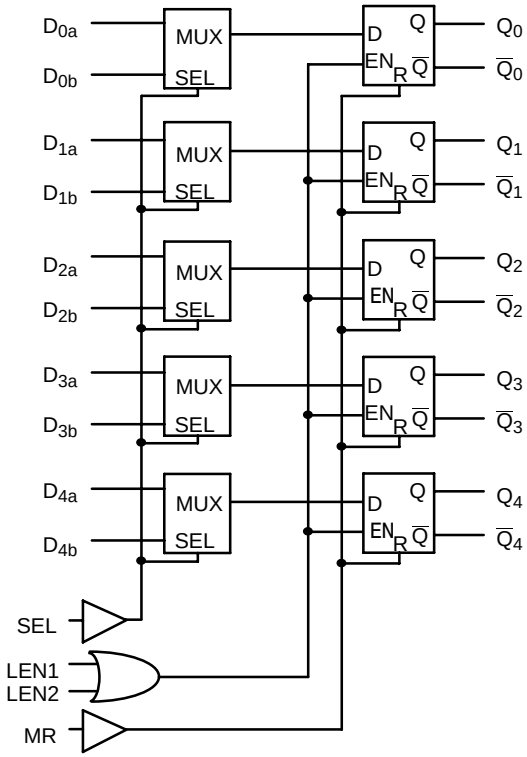
PIN DESCRIPTION

PIN	FUNCTION
$D_{0a} - D_{4a}$	ECL Input Data a
$D_{0b} - D_{4b}$	ECL Input Data b
SEL	ECL Data Select Input
LEN1, LEN2	ECL Latch Enables
MR	ECL Master Reset
$Q_0 - Q_4$, $\overline{Q}_0 - \overline{Q}_4$	ECL Differential Outputs
V_{CC}, V_{CCO}	Positive Supply
V_{EE}	Negative Supply

TRUTH TABLE

SEL	Data
H	a
L	b

LOGIC DIAGRAM



MAXIMUM RATINGS (Note 1)

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \leq V_{CC}$ $V_I \geq V_{EE}$	6 −6	V
I_{out}	Output Current	Continuous Surge		50 100	mA mA
T_A	Operating Temperature Range			0 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 LFPM 500 LFPM	28 PLCC 28 PLCC	63.5 43.5	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	28 PLCC	22 to 26	°C/W
T_{sol}	Wave Solder	<2 to 3 sec @ 248°C		265	°C

1. Maximum Ratings are those values beyond which device damage may occur.

10E SERIES PECL DC CHARACTERISTICS V_{CCx}= 5.0 V; V_{EE}= 0.0 V (Note 2)

		0°C			25°C			85°C			
Symbol	Characteristic	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Unit
I_{EE}	Power Supply Current		76	91		76	91		76	91	mA
V_{OH}	Output HIGH Voltage (Note 3)	3980	4070	4160	4020	4105	4190	4090	4185	4280	mV
V_{OL}	Output LOW Voltage (Note 3)	3050	3210	3370	3050	3210	3370	3050	3227	3405	mV
V_{IH}	Input HIGH Voltage	3830	3995	4160	3870	4030	4190	3940	4110	4280	mV
V_{IL}	Input LOW Voltage	3050	3285	3520	3050	3285	3520	3050	3302	3555	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.25		0.3	0.2		μA

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

2. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.06 V.
3. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2 V.

10E SERIES NECL DC CHARACTERISTICS V_{CCx}= 0.0 V; V_{EE}= −5.0 V (Note 4)

		0°C			25°C			85°C			
Symbol	Characteristic	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Unit
I_{EE}	Power Supply Current		76	91		76	91		76	91	mA
V_{OH}	Output HIGH Voltage (Note 5)	−1020	−930	−840	−980	−895	−810	−910	−815	−720	mV
V_{OL}	Output LOW Voltage (Note 5)	−1950	−1790	−1630	−1950	−1790	−1630	−1950	−1773	−1595	mV
V_{IH}	Input HIGH Voltage	−1170	−1005	−840	−1130	−970	−810	−1060	−890	−720	mV
V_{IL}	Input LOW Voltage	−1950	−1715	−1480	−1950	−1715	−1480	−1950	−1698	−1445	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.065		0.3	0.2		μA

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

4. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.06 V.
5. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2 V.

100E SERIES PECL DC CHARACTERISTICS V_{CCx}= 5.0 V; V_{EE}= 0.0 V (Note 6)

		0°C			25°C			85°C			
Symbol	**Characteristic**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
I_{EE}	Power Supply Current		76	91		76	91		87	105	mA
V_{OH}	Output HIGH Voltage (Note 7)	3975	4050	4120	3975	4050	4120	3975	4050	4120	mV
V_{OL}	Output LOW Voltage (Note 7)	3190	3295	3380	3190	3255	3380	3190	3260	3380	mV
V_{IH}	Input HIGH Voltage	3835	3975	4120	3835	3975	4120	3835	3975	4120	mV
V_{IL}	Input LOW Voltage	3190	3355	3525	3190	3355	3525	3190	3355	3525	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.25		0.5	0.2		μA

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

6. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.8 V.
7. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2 V.

100E SERIES NECL DC CHARACTERISTICS V_{CCx}= 0.0 V; V_{EE}= −5.0 V (Note 8)

		0°C			25°C			85°C			
Symbol	**Characteristic**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
I_{EE}	Power Supply Current		76	91		76	91		87	105	mA
V_{OH}	Output HIGH Voltage (Note 9)	−1025	−950	−880	−1025	−950	−880	−1025	−950	−880	mV
V_{OL}	Output LOW Voltage (Note 9)	−1810	−1705	−1620	−1810	−1745	−1620	−1810	−1740	−1620	mV
V_{IH}	Input HIGH Voltage	−1165	−1025	−880	−1165	−1025	−880	−1165	−1025	−880	mV
V_{IL}	Input LOW Voltage	−1810	−1645	−1475	−1810	−1645	−1475	−1810	−1645	−1475	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.25		0.5	0.2		μA

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

8. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.8 V.
9. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2 V.

AC CHARACTERISTICS V_{CCx}= 5.0 V; V_{EE}= 0.0 V or V_{CCx}= 0.0 V; V_{EE}= −5.0 V (Note 1.)

Symbol	Characteristic	0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{MAX}	Maximum Toggle Frequency	700	1100		700	1100		700	1100		MHz
t_{PLH}	Propagation Delay to Output										ps
t_{PHL}	D	325	500	700	325	500	700	325	500	700	
	SEL	475	650	925	475	650	925	475	650	925	
	LEN	350	500	750	350	500	750	350	500	750	
	MR	450	600	800	450	600	800	450	600	800	
t_s	Setup Time										ps
	D	300	100		300	100		300	100		
	SEL	500	250		500	250		500	250		
t_h	Hold Time										ps
	D	300	−100		300	−100		300	−100		
	SEL	200	− 250		200	− 250		200	− 250		
t_{RR}	Reset Recovery Time	800	600		800	600		800	600		ps
t_{PW}	Minimum Pulse Width										ps
	MR	400			400			400			
t_{SKEW}	Within-Device Skew (Note 11)		50			50			50		ps
t_{JITTER}	Random Clock Jitter (RMS)		< 1			< 1			< 1		ps
t_r	Rise/Fall Times										ps
t_f	(20 - 80%)	300	475	800	300	475	800	300	475	800	

NOTE: Devices are designed to meet the AC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

10. 10 Series: V_{EE} can vary −0.46 V / +0.06 V.
    100 Series: V_{EE} can vary −0.46 V / +0.8 V.
11. Within-device skew is defined as identical transitions on similar paths through a device.

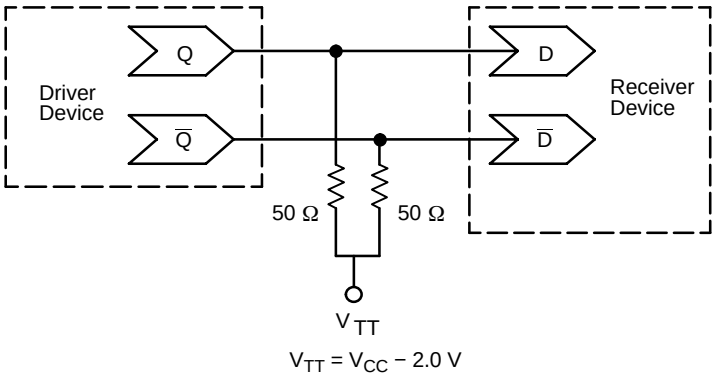


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020 − Termination of ECL Logic Devices.)

Resource Reference of Application Notes

AN1404 − ECLinPS Circuit Performance at Non−Standard V_{IH} Levels

AN1405 − ECL Clock Distribution Techniques

AN1406 − Designing with PECL (ECL at +5.0 V)

AN1503 − ECLinPS I/O SPICE Modeling Kit

AN1504 − Metastability and the ECLinPS Family

AN1568 − Interfacing Between LVDS and ECL

AN1596 − ECLinPS Lite Translator ELT Family SPICE I/O Model Kit

AN1650 − Using Wire−OR Ties in ECLinPS Designs

AN1672 − The ECL Translator Guide

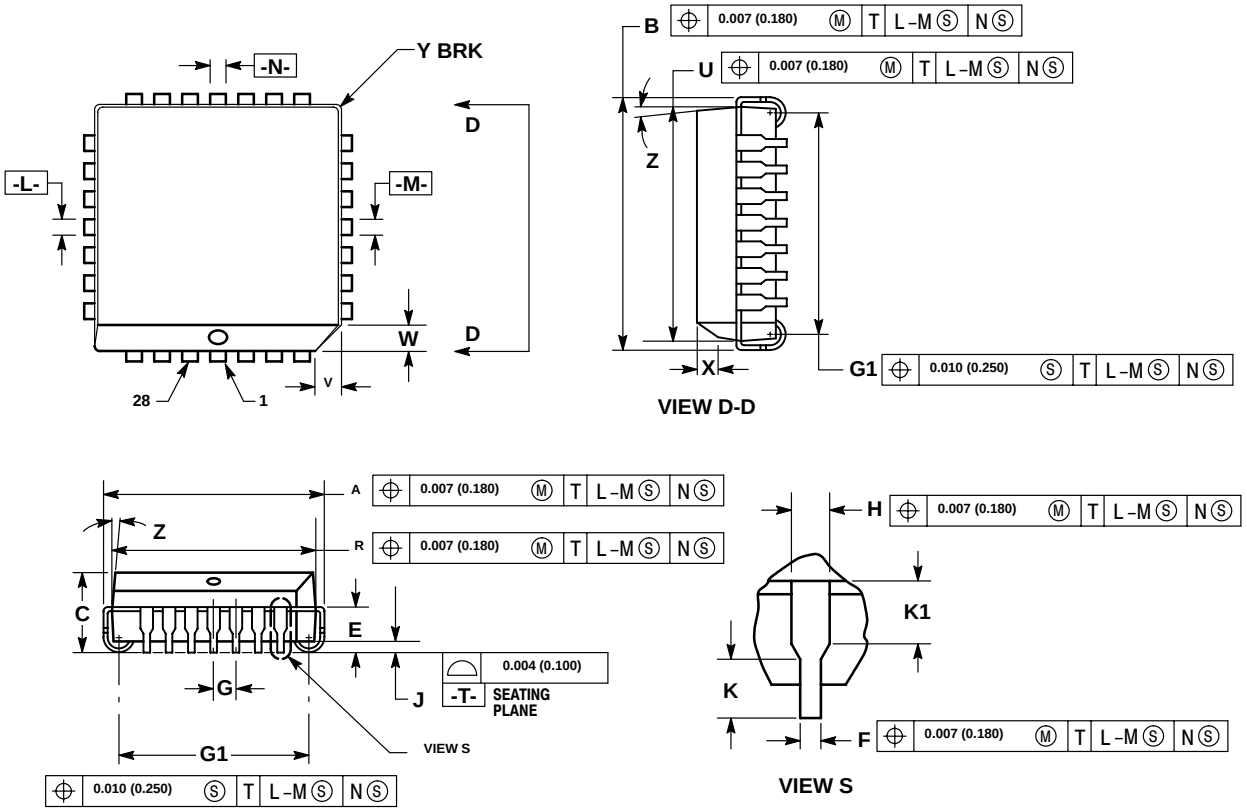
AND8001 − Odd Number Counters Design

AND8002 − Marking and Date Codes

AND8020 − Termination of ECL Logic Devices

PACKAGE DIMENSIONS

PLCC−28
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 776−02
ISSUE E



NOTES:
1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIM G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
3. DIM R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	—	1.02	—

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